

# 5<sup>TH</sup> [www.icmsn.org](http://www.icmsn.org) **ICMSN 2021**

## 2021 The 5th International Conference on Materials Sciences and Nanomaterials

London, United Kingdom | July 13-15, 2021

### Important Dates

Submission Deadline	June 10, 2021
Notification Deadline	June 25, 2021
Registration Deadline	July 01, 2021

### Submission Methods

1. Online Submission System

(<http://confsys.iconf.org/submission/icmsn2021>)

2. Send directly to: [icmsn@cbees.net](mailto:icmsn@cbees.net)

For more information about submission, please visit:

<http://www.icmsn.org/sub.html>

### Publication



Materials Science Forum (ISSN print 0255-5476 / ISSN web 1662-9752), which is indexed by Ei Compendex, Scopus, Chemical Abstracts Service (CAS), REAXYS, Chimica, etc.

### Publication History

ICMSN 2020	Key Engineering Materials (Vol. 878) ISBN: 978-3-0357-1749-5
ICMSN 2019	Materials Science Forum (Vol. 982) ISBN: 978-3-0357-1555-2
ICMSN 2018	Materials Science Forum (Vol. 962) ISBN: 978-3-0357-1416-6
ICMSN 2017	IOP Conference Series: Materials Science and Engineering (Vol. 230) ISSN: 1757-8981

### Speakers



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Hong Kong



Prof. Sotirios Grammatikos  
Norwegian University of Science  
and Technology



Assoc. Prof. Christèle Jaillet-Bartholome  
University of Bordeaux, France

### Conference Topics

1. Nanomaterials
2. Electronic Materials
3. Material Chemistry
4. Materials Processing Engineering
5. Structural Material

For more topics, please visit:

<http://www.icmsn.org/cfp.html>

### Contact Us

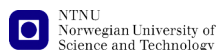
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